

**REMARKS**

The Office Action dated October 10, 2007 has been reviewed and carefully considered. Claims 1, 2, and 5-7 have been amended. Claims 1 and 2 are the only independent claims. Reconsideration of the above-identified application, as amended and in view of the following remarks, is respectfully requested.

The Examiner has objected to the claims 5-7 as being in improper form. Application has amended each of these claims so that it does not depend on a multiple dependent claim. With these amendments, Applicant believes that the reason for the Examiner's objection has been overcome. Applicant respectfully requests the objections be withdrawn.

Claims 1-3 stand rejected under 35 USC 102(b) as being anticipated by Kanaya et al., U.S. Patent No. 6,169,593 (Hereinafter "Kanaya"). The Office Action recites that claims 5-7 were not treated on the merits due to their improper form. The status of claim 4 is unclear.

The present invention relates to an electronic apparatus provided with a wiring terminal. More specifically, the invention relates to an electronic apparatus comprising a wiring terminal for connecting to a terminal of peripheral circuitry. In particular, claim 1 as currently amended, recites:

An electronic apparatus comprising:

a conductive layer having a top surface and a bottom surface, the bottom surface in at least partial contact with a substrate, the electronic apparatus further comprising a metal layer of a material having a resistivity lower than that of the conductive layer, the metal layer being extended on the top surface of the conductive layer, the conductive layer having an oxidation resistivity higher than that of the metal layer and forming a terminal for connecting to peripheral circuitry, wherein:

the metal layer extends on an extending portion of the top surface of the conductive layer outside the terminal of the conductive layer, and/or on the periphery of or in the vicinity of a coupling area for making the conductive layer to be exposed to the exterior within an area of the terminal of the conductive layer; and

there is provided an electrically insulating layer which covers at least a part of the terminal of the conductive layer and the whole of the metal layer and which extends on the area other than the coupling area within the area of the terminal of the conductive layer.

The above features of the claim are illustrated in the embodiment depicted in Fig. 2 of the present invention wherein: the bottom surface of conductive layer 10 is in contact with the substrate 8 while the metal layer 20 is extended on the top surface of the conductive layer 10. As described in paragraph [0019] of the published application, this arrangement achieves an advantage over the prior art: "the metal layer with a low resistivity reduces the connection resistance of the conductive layer with a high resistivity, and at least a main portion of the corrosion-prone metal layer is protected by the insulating layer."

Kanaya et al. relates to a method for producing a circuit board in a reflection-type liquid crystal display device. The Office Action points to Figs. 12B and 9 of Kanaya as teaching the features of claim 1. Fig. 12B depicts "an ITO layer [item 28] the "conductive

layer" as referenced in the Office Action] ... formed on the gate insulating layer 24" (col. 8, lines 47-79). Further, Fig. 12B depicts the first terminal electrode layer 22 [the "metal layer" as referenced in the Office Action] as being in contact with the "substrate 20." Thus as illustrated, Fig. 12B fails to teach the features of the present invention whereby the bottom surface of conductive layer 10 (Kanaya's item 28) is in contact with the substrate 8 (Kanaya's item 20) while the metal layer 20 (Kanaya's item 22) is extended on the top surface of the conductive layer 10 (Kanaya's item 28). Fig. 9 contains the same structure hierarchy as that illustrated in Fig. 12B and accordingly fails to remedy the deficiencies of Kanaya in teaching the invention as claimed in claim 1.

A claim is anticipated only if each and every element recited therein is expressly or inherently described in a single prior art reference. Kanaya cannot be said to anticipate the present invention, because Kanaya fails to disclose each and every element recited. As shown, Kanaya fails to disclose the limitation of "a conductive layer having a top surface and a bottom surface, the bottom surface in at least partial contact with a substrate, the electronic apparatus further comprising a metal layer ..., the metal layer being extended on the top surface of the conductive layer." Claim 2 contains a similar feature and is patentable over Kanaya for at least the same reasons.

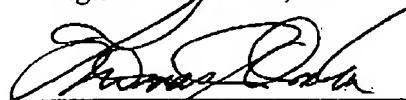
Having shown that Kanaya fails to disclose each and every element claimed, applicant submits that claims 1 and 2 are allowable over Kanaya. Applicant respectfully requests reconsideration, withdrawal of the rejection and allowance of claims 1 and 2.

With regard to claims 3-7, these claims ultimately depend from one of the independent claims, which have been shown to be not anticipated and allowable in view of the cited references. Accordingly, claims 3-7 are also allowable by virtue of their dependence from an allowable base claim.

For all the foregoing reasons, it is respectfully submitted that all the present claims are patentable in view of the cited references. A Notice of Allowance is respectfully requested.

Respectfully submitted,

Dan Piotrowski  
Registration No. 42,079



By: Thomas Onka  
Attorney for Applicant  
Registration No. 42,053

Date: January 8, 2008

**Mail all correspondence to:**  
Dan Piotrowski, Registration No. 42,079  
US PHILIPS CORPORATION  
P.O. Box 3001  
Briarcliff Manor, NY 10510-8001  
Phone: (914) 333-9624  
Fax: (914) 332-0615

Certificate of Mailing/Transmission Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to MAIL STOP AMENDMENT, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA. 22313-1450 or transmitted by facsimile to the U.S. Patent and Trademark Office, Fax No (571) 273-8300 on 1/8/08

  
(Name of Registered Rep.)

 1/8/08  
(Signature and Date)